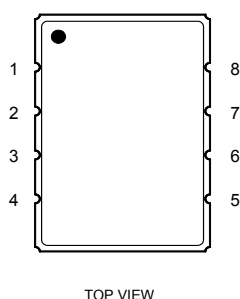


Electrical Connections

Terminal Number	Connection
1	V _{CC}
2	Ground
3	NC or Ground
4	Q Output
5	Q Output
6	Ground
7	
8	ENABLE
LID	Ground

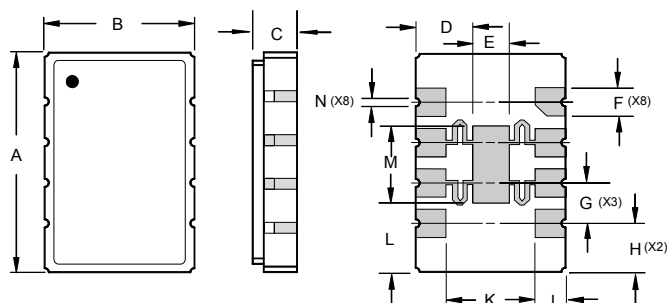


TOP VIEW

Case Design

All pads consist of 30 microinches (min) electroless gold on 50 microinches (min) electroless nickel over base metal. The metallic center pad was designed for mechanical support. Grounding of this pad is critical to the performance of this high frequency Clock.

Lid symbolization, including terminal 1 locator dot, are in contrasting ink. Symbolization varies by model number. For purposes of illustration, only terminal 1 dot is shown.



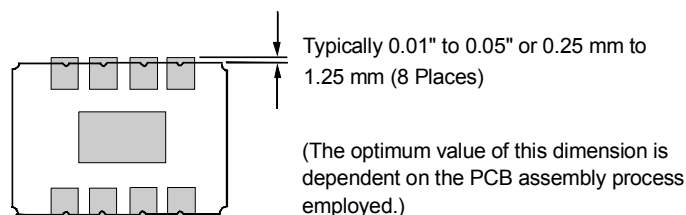
Footprint

Actual size footprint:

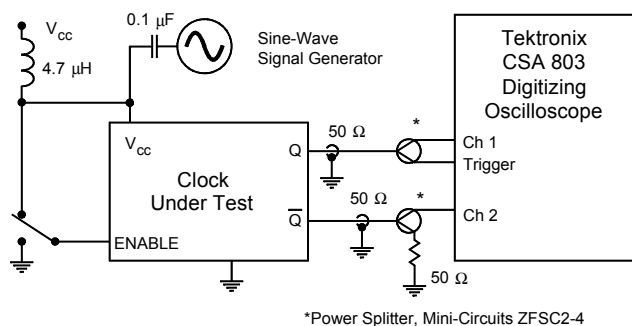


Typical Printed Circuit Board Land Pattern

A typical land pattern for a circuit board is shown below. Grounding of the metallic center pad is critical to the performance of this high frequency Clock.



Typical Test Circuit

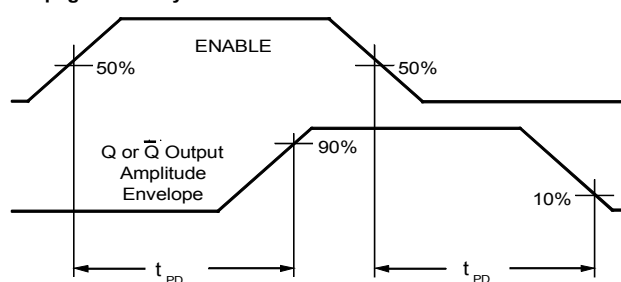


Electrical Characteristics

Dimensions	Millimeters		Inches	
	Min	Max	Min	Max
A	13.46	13.97	0.530	0.550
B	9.14	9.66	0.360	0.380
C	2.05 Nominal		0.081 Nominal	
D	3.56 Nominal		0.141 Nominal	
E	2.24 Nominal		0.088 Nominal	
F	1.27 Nominal		0.050 Nominal	
G	2.54 Nominal		0.100 Nominal	
H	3.05 Nominal		0.120 Nominal	
J	1.93 Nominal		0.076 Nominal	
K	5.54 Nominal		0.218 Nominal	
L	4.32 Nominal		0.170 Nominal	
M	4.83 Nominal		0.190 Nominal	
N	0.50 Nominal		0.020 Nominal	

Timing Definitions

Propagation Delay:



Symmetry:

